

## **Operational Amplifier Series**

# Automotive Ground Sense Operational Amplifiers



BA2904Yxxx-C, BA2902Yxx-C

## General Description

BA2904Yxxx-C,BA2902Yxx-C integrate two or four independent Op-Amps and ground sense input Amplifier on a single chip. These Op-Amps have some features of high-gain, low power consumption, and can operate from +3V to +36V (single power supply ). BA2904Yxxx-C, BA2902Yxx-C are manufactured for automotive requirements of engine control unit, electric power steering, and so on.

## Features

- AEC-Q100 Qualified
- Single or dual power supply operation
- Wide operating supply voltage
- Standard Op-Amp Pin-assignments
- Common-mode Input Voltage Range includes ground level, allowing direct ground sensing
- Low supply current
- High open loop voltage gain
- Internal ESD protection circuit
- Wide temperature range

## Application

- Engine Control Unit
- Electric Power Steering (EPS)
- Anti-Lock Braking System (ABS)
- Automotive electronics

## Key Specifications

■ Wide operating supply voltage

Single supply: +3.0V to +36VDual supply:  $\pm 1.5V$  to  $\pm 18V$ 

Low supply current

 BA2904Yxxx-C
 0.5mA(Typ.)

 BA2902Yxx-C
 0.7mA(Typ.)

 Input bias current :
 20nA(Typ.)

 Input offset current :
 2nA(Typ.)

 Operating temperature range :
 -40°C to +125°C

 ◆Packages
 W(Typ.) x D(Typ.) x (Max.)

 SOP8
 5.00mm x 6.20mm x 1.71mm

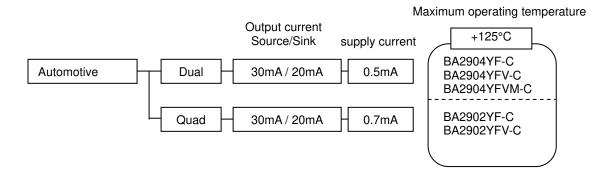
 SOP14
 8.70mm x 6.20mm x 1.71mm

 SSOP-B8
 3.00mm x 6.40mm x 1.35mm

 SSOP-B14
 5.00mm x 6.40mm x 1.35mm

 MSOP8
 2.90mm x 4.00mm x 0.90mm

## Selection Guide



OProduct structure: Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

## Simplified schematic

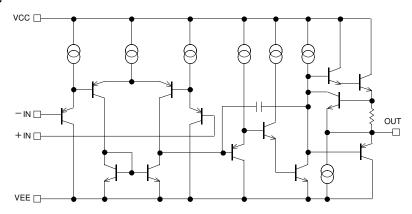
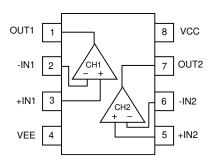


Figure 1. Simplified schematic (one channel only)

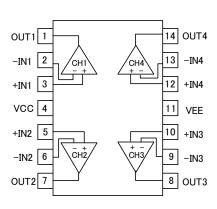
## ●Pin Configuration

BA2904YF-C: SOP8 BA2904YFV-C: SSOP-B8 BA2904YFVM-C: MSOP8



Pin No.	Pin name
1	OUT1
2	-IN1
3	+IN1
4	VEE
5	+IN2
6	-IN2
7	OUT2
8	VCC

BA2902YF-C: SOP14 BA2902YFV-C: SSOP-B14



Pin No.	Pin name
1	OUT1
2	-IN1
3	+IN1
4	VCC
5	+IN2
6	-IN2
7	OUT2
8	OUT3
9	-IN3
10	+IN3
11	VEE
12	+IN4
13	-IN4
14	OUT4

		Package		
SOP8	SSOP-B8	MSOP8	SOP14	SSOP-B14
BA2904YF-C	BA2904YFV-C	BA2904YFVM-C	BA2902YF-C	BA2902YFV-C

Ordering Information



Parts Number. BA2904Yxxx BA2902Yxx Package F: SOP8 SOP14 FV: SSOP-B8

SSOP-B14 FVM: MSOP8 Packaging and forming specification

C: Automotive (Engine control unit, EPS,

ABS, and so on)

E2: Embossed tape and reel

(SOP8/SOP14/SSOP-B8/SSOP-B14)

TR: Embossed tape and reel

(MSOP8)

●Line-up

Topr	Operating Supply Voltage	Number of channels	Pa	ckage	Orderable Parts Number
			SOP8	Reel of 2500	BA2904YF-CE2
		Dual	SSOP-B8	Reel of 2500	BA2904YFV-CE2
-40°C to +125°C	+3.0V to +36V		MSOP8	Reel of 3000	BA2904YFVM-CTR
		Quad	SOP14	Reel of 2500	BA2902YF-CE2
	Qı		SSOP-B14	Reel of 2500	BA2902YFV-CE2

● Absolute Maximum Ratings(Ta=25°C)

Parameter		Symbol	Ratings	Unit
Supply Voltage		VCC-VEE	+36	V
Power Dissipation		SOP8	770 <sup>*1*6</sup>	
		SSOP-B8	620 <sup>*2*6</sup>	
	Pd	MSOP8	580 <sup>*3*6</sup>	mW
		SOP14	560 <sup>*4*6</sup>	
		SSOP-B14	870 <sup>*5*6</sup>	
Differential Input Voltage *7		Vid	+36	V
Input Common-mode Voltage Range		Vicm	(VEE-0.3) to (VEE+36)	V
Input Current *8		li	-10	mA
Operating Supply Voltage		Vopr	+3.0 to +36 (±1.5 to ±18)	V
Operating Temperature Range	Topr		-40 to +125	°C
Storage Temperature Range		Tstg	-55 to +150	°C
Maximum Junction Temperature		Tjmax +150		°C

Note: Absolute maximum rating item indicates the condition which must not be exceeded.

Application if voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

The input current can be set to less than the rated current by adding a limiting resistor.

<sup>\*1</sup> To use at temperature above Ta=25°C reduce 6.2mW/°C.

<sup>\*2</sup> To use at temperature above Ta=25°C reduce 5.0mW/°C.

<sup>\*3</sup> To use at temperature above Ta=25°C reduce 4.7mW/°C.

<sup>\*4</sup> To use at temperature above Ta=25°C reduce 4.5mW/°C.

<sup>\*5</sup> To use at temperature above Ta=25°C reduce 7.0mW/°C. \*6 Mounted on a FR4 glass epoxy PCB(70mm×70mm×1.6mm).

<sup>\*7</sup> The voltage difference between inverting input and non-inverting input is the differential input voltage. Then input pin voltage is set to more than VEE.

<sup>\*8</sup> An excessive input current will flow when input voltages of lesser than VEE-0.6V are applied.

## **●**Electrical Characteristics

OBA2904Yxxx-C (Unless otherwise specified VCC=+5V, VEE=0V)

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Parameter	Symbol	Temperature		Limits	T	Unit	Conditions	
		Range	Min.	Тур.	Max.			
Input Offset Voltage *9	Vio	25°C	1	2	3.5	mV	OUT=1.4V	
input Onset Voltage	VIO	Full range	-	-	4	IIIV	VCC=5 to 30V, OUT=1.4V	
	E-	25°C	-	2	40	^	OUT 4 AV	
Input Offset Current *9	lio	Full range	-	-	50	nA	OUT=1.4V	
Input Bias Current *9	II-	25°C	-	20	60	Λ	OUT 1 4V	
input Blas Current	lb	Full range	-	-	100	nA	OUT=1.4V	
Supply Current	ICC	25°C	-	0.5	1.2	mA	RL=∞, All Op-Amps	
Supply Current	100	Full range	-	-	1.2	IIIA	TIL=~, All Op-Allips	
		25°C	3.5	-	-		RL=2kΩ	
Maximum Output Voltage (High)	VOH	Full range	3.2	-	-	V	TL=ZN12	
		ruii range	27	28	-		VCC=30V, RL=10kΩ	
Maximum Output Voltage(Low)	VOL	Full range	-	5	20	mV	RL=∞, All Op-Amps	
Large Signal Voltage Gain	Av	25°C	25	100	-	V/mV	RL≧2kΩ, VCC=15V	
Large Signal Voltage Gain	AV	Full range	25	-	-	V/IIIV	OUT=1.4 to 11.4V	
Input Common-mode	Vicm	25°C	0	-	VCC-1.5	V	(VCC-VEE)=5V,	
Voltage Range	VICITI	Full range	0	-	VCC-2.0	V	OUT=VEE+1.4V	
Common-mode Rejection Ratio	CMRR	25°C	65	80	-	dB	OUT=1.4V	
Power Supply Rejection Ratio	PSRR	25°C	65	100	-	dB	VCC=5 to 30V	
Output Source Current *10	lagurag	25°C	20	30	-	A	+IN=1V, -IN=0V OUT=0V	
Output Source Current	Isource	Full range	10	-	-	mA	1CH is short circuit	
		25°C	10	20	-	m ^	+IN=0V, -IN=1V OUT=5V	
Output Sink Current *10	Isink	Full range	2	-	-	mA	1CH is short circuit	
		25°C	12	40	-	μΑ	+IN=0V, -IN=1V OUT=200mV	
Slew Rate	SR	25°C	-	0.2	-	V/µs	VCC=15V, Av=0dB RL=2kΩ, CL=100pF	
Gain Bandwidth Product	GBW	25°C	-	0.5	-	MHz	VCC=30V, RL=2kΩ CL=100pF	
Channel Separation	CS	25°C	-	120	-	dB	f=1kHz, input referred	
*9 Absolute value	i i							

<sup>\*9</sup> Absolute value

<sup>\*10</sup> Under high temperatures, please consider the power dissipation when selecting the output current.

When the output terminal is continuously shorted the output current reduces the internal temperature by flushing.

OBA2902Yxx-C (Unless otherwise specified VCC=+5V, VEE=0V)

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Parameter	Symbol	Temperature		Limits		Unit	Conditions	
i arameter	Cymbol	Range	Min.	Тур.	Max.	Offic	Conditions	
Input Offset Voltage *11	Vio	25°C	-	2	3.8	mV	OUT=1.4V	
input Onset voltage	VIO	Full range	-	-	4	IIIV	VCC=5 to 30V, OUT=1.4V	
Input Offset Current *11	lio	25°C	-	2	40	n 1	OUT=1.4V	
input Oliset Current	IIO	Full range	-	-	50	nA	001=1.40	
Input Bias Current *11	lb	25℃	ı	20	60	nA	OUT=1.4V	
Input bias Current	ID	Full range	-	-	100	IIA	001=1.44	
Supply Current	ICC	25℃	ı	0.7	2	mA	RL=∞, All Op-Amps	
Supply Current	100	Full range	-	-	3	ША	TL=**, All Op-Allips	
		25°C	3.5	-	-		RL=2kΩ	
Maximum Output Voltage (High)	VOH	Full range	3.2	-	-	V	TIL-ZNS2	
		i uli range	27	28	-		VCC=30V, RL=10kΩ	
Maximum Output Voltage(Low)	VOL	Full range	-	5	20	mV	RL=∞, All Op-Amps	
Large Signal Voltage Gain	Av	25℃	25	100	1	V/mV	RL≧2kΩ, VCC=15V	
Large Signal Vollage Gain	AV	Full range	25	-	-	V/IIIV	OUT=1.4 to 11.4V	
Input Common-mode	Vicm	25°C	0	-	VCC-1.5	V	(VCC-VEE)=5V,	
Voltage Range	VICITI	Full range	0	-	VCC-2.0	V	OUT=VEE+1.4V	
Common-mode Rejection Ratio	CMRR	25°C	65	80	-	dB	OUT=1.4V	
Power Supply Rejection Ratio	PSRR	25℃	65	100	-	dB	VCC=5 to 30V	
Output Source Current *12	Isource	25℃	20	30	1	mA	+IN=1V, -IN=0V OUT=0V	
Output Source Gurrent	isource	Full range	10	-	-	ША	1CH is short circuit	
		25°C	10	20	-	mA	+IN=0V, -IN=1V OUT=5V	
Output Sink Current *12	Isink	Full range	2	-	-	11174	1CH is short circuit	
		25°C	12	40	-	μA	+IN=0V, -IN=1V OUT=200mV	
Slew Rate	SR	25°C	-	0.2	-	V/µs	VCC=15V, Av=0dB RL=2kΩ, CL=100pF	
Gain Bandwidth Product	GBW	25°C	-	0.5	-	MHz	VCC=30V, RL=2kΩ CL=100pF	
Channel Separation	cs	25°C	-	120	-	dB	f=1kHz, input referred	
*** **								

<sup>\*11</sup> Absolute value

<sup>\*12</sup> Under high temperatures, please consider the power dissipation when selecting the output current.

When the output terminal is continuously shorted the output current reduces the internal temperature by flushing.

## **Description of Electrical Characteristics**

Described below are descriptions of the relevant electrical terms used in this datasheet. Items and symbols used are also shown. Note that item name and symbol and their meaning may differ from those on another manufacturer's document or general document.

## 1. Absolute maximum ratings

Absolute maximum rating items indicate the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

## 1.1 Supply Voltage (VCC-VEE)

Indicates the maximum voltage that can be applied between the positive power supply terminal and negative power supply terminal without deterioration or destruction of characteristics of internal circuit.

## 1.2 Differential Input Voltage (Vid)

Indicates the maximum voltage that can be applied between non-inverting and inverting terminals without damaging the IC.

## 1.3 Input Common-mode Voltage Range (Vicm)

Indicates the maximum voltage that can be applied to the non-inverting and inverting terminals without deterioration or destruction of electrical characteristics. Input common-mode voltage range of the maximum ratings does not assure normal operation of IC. For normal operation, use the IC within the input common-mode voltage range characteristics.

## 1.4 Operating and Storage Temperature Ranges (Topr,Tstg)

The operating temperature range indicates the temperature range within which the IC can operate. The higher the ambient temperature, the lower the power consumption of the IC. The storage temperature range denotes the range of temperatures the IC can be stored under without causing excessive deterioration of the electrical characteristics.

## 1.5 Power Dissipation (Pd)

Indicates the power that can be consumed by the IC when mounted on a specific board at the ambient temperature 25°C (normal temperature). As for package product, Pd is determined by the temperature that can be permitted by the IC in the package (maximum junction temperature) and the thermal resistance of the package.

## 2. Electrical characteristics

## 2.1 Input Offset Voltage (Vio)

Indicates the voltage difference between non-inverting terminal and inverting terminals. It can be translated into the input voltage difference required for setting the output voltage at 0 V.

## 2.2 Input Offset Current (lio)

Indicates the difference of input bias current between the non-inverting and inverting terminals.

## 2.3 Input Bias Current (lb)

Indicates the current that flows into or out of the input terminal. It is defined by the average of input bias currents at the non-inverting and inverting terminals.

## 2.4 Supply Current (ICC)

Indicates the current that flows within the IC under specified no-load conditions.

## 2.5 Maximum Output Voltage (High) / Maximum Output Voltage (Low) (VOH/VOL)

Indicates the voltage range of the output under specified load condition. It is typically divided into high-level output voltage and low-level output voltage. High-level output voltage indicates the upper limit of output voltage while Low-level output voltage indicates the lower limit.

## 2.6 Large Signal Voltage Gain (Av)

Indicates the amplifying rate (gain) of output voltage against the voltage difference between non-inverting terminal and inverting terminal. It is normally the amplifying rate (gain) with reference to DC voltage.

Av = (Output voltage) / (Differential input voltage)

## 2.7 Input Common-mode Voltage Range (Vicm)

Indicates the input voltage range where IC normally operates.

## 2.8 Common-mode Rejection Ratio (CMRR)

Indicates the ratio of fluctuation of input offset voltage when the input common mode voltage is changed. It is normally the fluctuation of DC.

CMRR = (Change of Input common-mode voltage)/(Input offset fluctuation)

## 2.9 Power Supply Rejection Ratio (PSRR)

Indicates the ratio of fluctuation of input offset voltage when supply voltage is changed. It is normally the fluctuation of DC.

PSRR= (Change of power supply voltage)/(Input offset fluctuation)

## 2.10 Output Source Current/ Output Sink Current (Isource / Isink)

The maximum current that can be output from the IC under specific output conditions. The output source current indicates the current flowing out from the IC, and the output sink current indicates the current flowing into the IC.

## 2.11 Slew Rate (SR)

Indicates the ratio of the change in output voltage with time when a step input signal is applied.

## 2.12 Gain Bandwidth Product (GBW)

The product of the open-loop voltage gain and the frequency at which the voltage gain decreases 6dB/octave.

## 2.13 Channel Separation (CS)

Indicates the fluctuation in the output voltage of the driven channel with reference to the change of output voltage of the channel which is not driven.

## ● Typical Performance Curves

OBA2904Yxxx-C

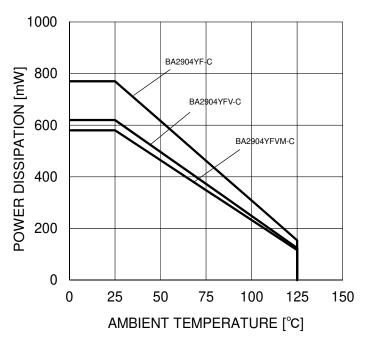


Figure 2.
Derating Curve

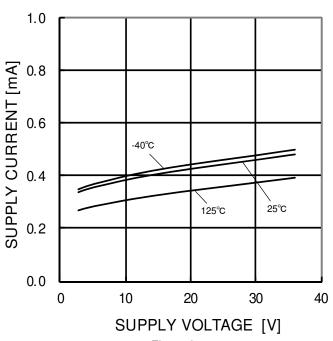


Figure 3.
Supply Current – Supply Voltage

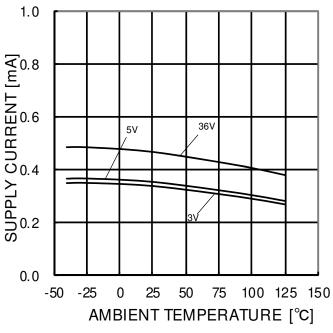


Figure 4.
Supply Current – Ambient Temperature

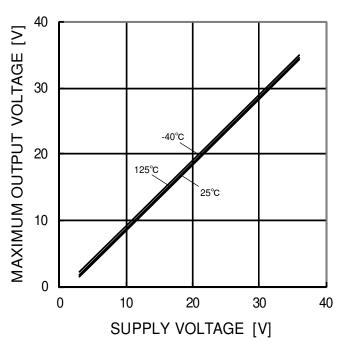


Figure 5.

Maximum Output Voltage – Supply Voltage  $(RL=10k\Omega)$ 

# ●Typical Performance Curves -Continued OBA2904Yxxx-C

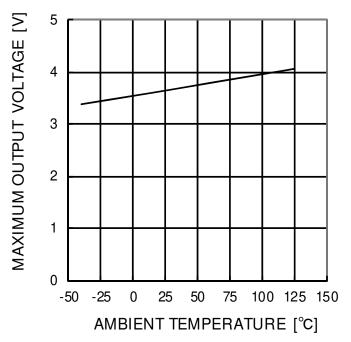


Figure 6.
Maximum Output Voltage – Ambient Temperature (VCC=5V, RL=2kΩ)

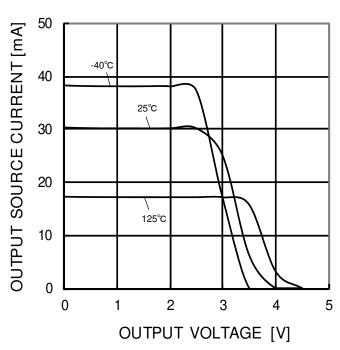


Figure 7.
Output Source Current – Output Voltage (VCC=5V)

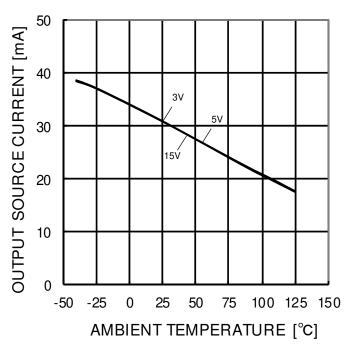


Figure 8.
Output Source Current – Ambient Temperature (OUT=0V)

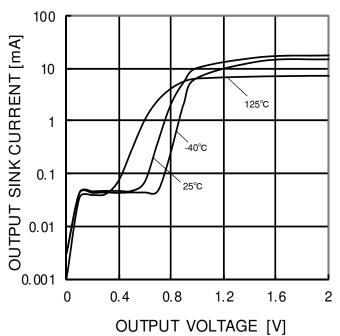


Figure 9.
Output Sink Current – Output Voltage (VCC=5V)

OBA2904Yxxx-C

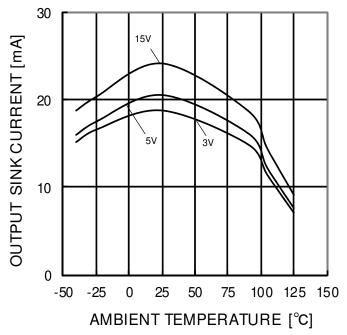


Figure 10.
Output Sink Current – Ambient Temperature
(OUT=VCC)

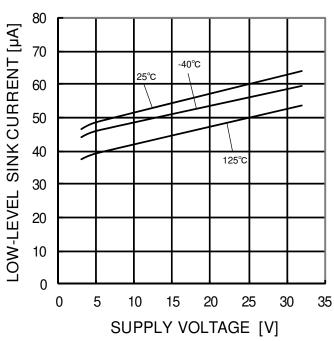


Figure 11.
Low Level Sink Current – Supply Voltage (OUT=0.2V)

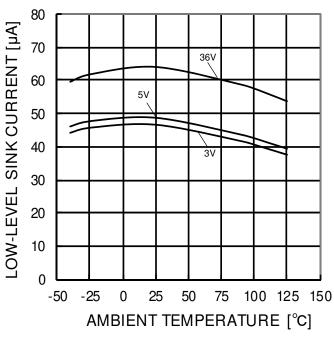


Figure 12.
Low Level Sink Current – Ambient Temperature (OUT=0.2V)

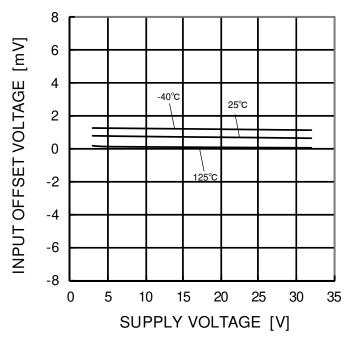


Figure 13.
Input Offset Voltage – Supply Voltage
(Vicm=0V, OUT=1.4V)

OBA2904Yxxx-C

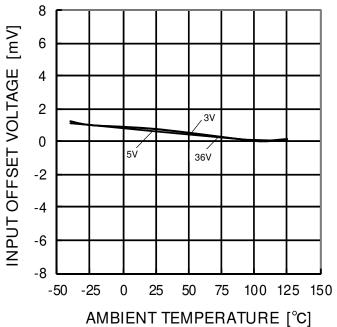


Figure 14.
Input Offset Voltage – Ambient Temperature (Vicm=0V, OUT=1.4V)

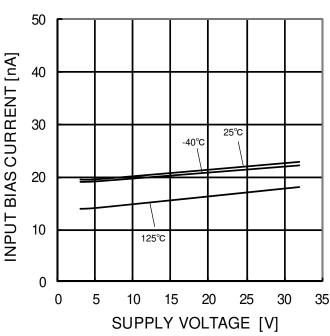


Figure 15.
Input Bias Current – Supply Voltage
(Vicm=0V, OUT=1.4V)

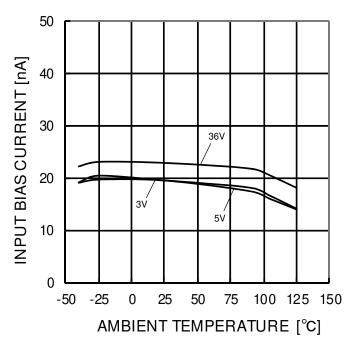


Figure 16.
Input Bias Current – Ambient Temperature (Vicm=0V, OUT=1.4V)

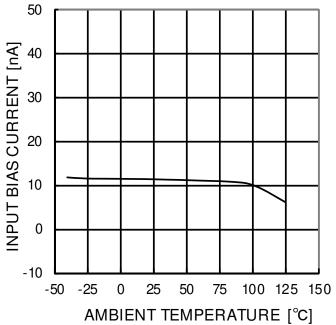
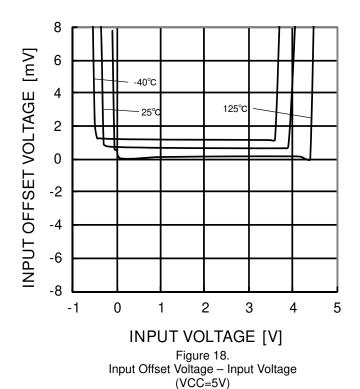
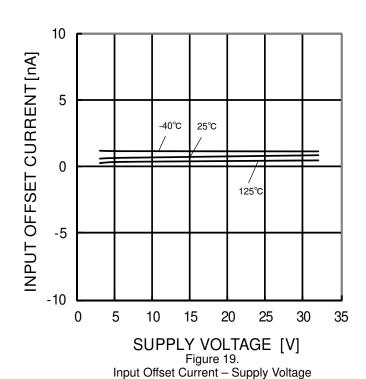


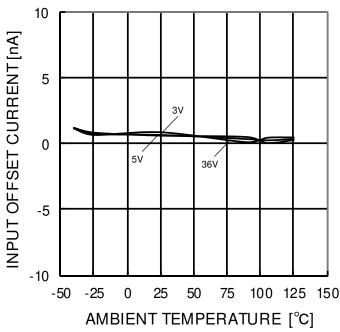
Figure 17.
Input Bias Current – Ambient Temperature (VCC=30V, Vicm=28V, OUT=1.4V)

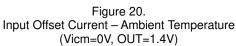
OBA2904Yxxx-C





(Vicm=0V, OUT=1.4V)





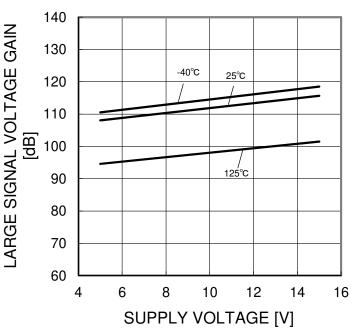


Figure 21. Large Signal Voltage Gain – Supply Voltage  $(RL=2k\Omega)$ 

# ●Typical Performance Curves -Continued OBA2904Yxxx-C

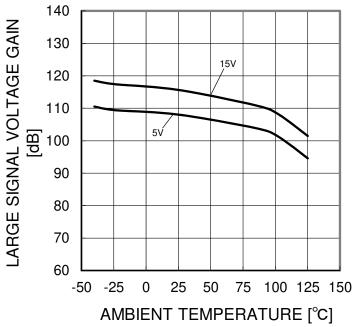


Figure 22.

Large Signal Voltage Gain – Ambient Temperature  $(RL=2k\Omega)$ 

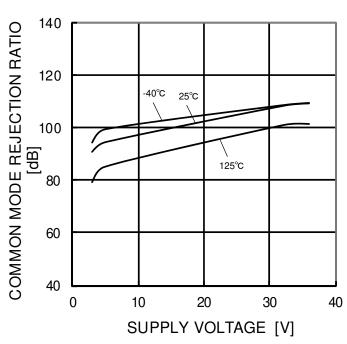


Figure 23.
Common Mode Rejection Ratio
– Supply Voltage

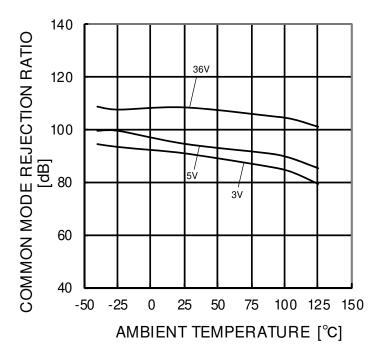


Figure 24.
Common Mode Rejection Ratio
– Ambient Temperature

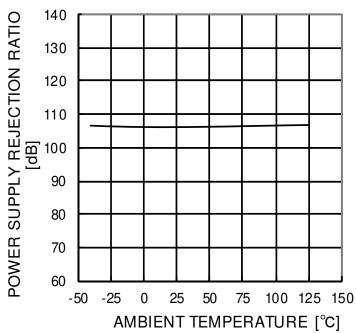


Figure 25.
Power Supply Rejection Ratio
– Ambient Temperature

## **●**Typical Performance Curves

OBA2902Yxx-C

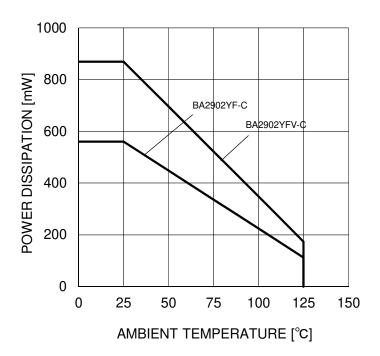


Figure 26.
Derating Curve

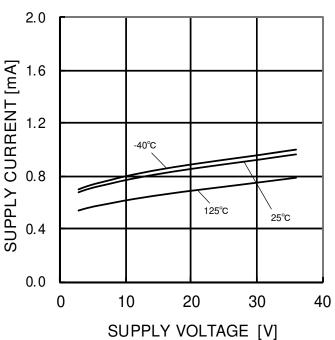
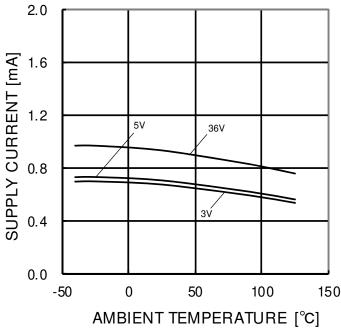
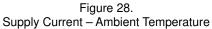


Figure 27. Supply Current – Supply Voltage





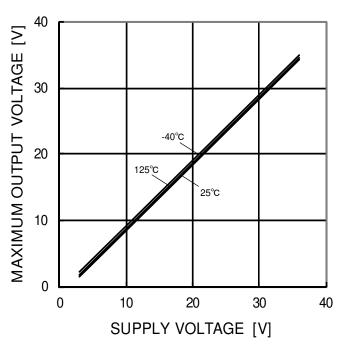


Figure 29.

Maximum Output Voltage – Supply Voltage  $(RL=10k\Omega)$ 

# ●Typical Performance Curves -Continued OBA2902Yxx-C

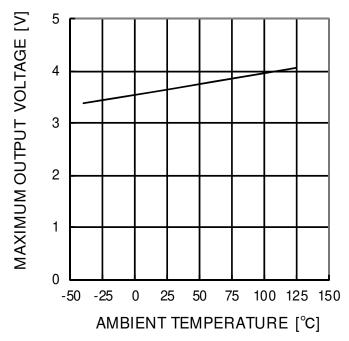


Figure 30.

Maximum Output Voltage – Ambient Temperature (VCC=5V, RL=2kΩ)

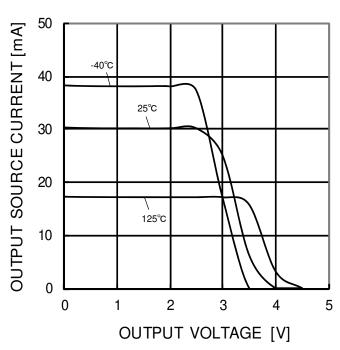


Figure 31.
Output Source Current – Output Voltage (VCC=5V)

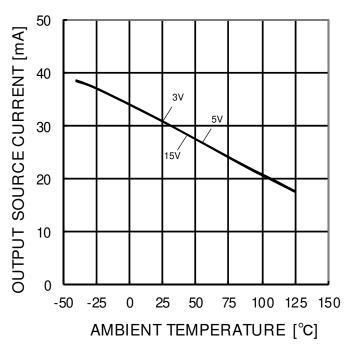


Figure 32.
Output Source Current – Ambient Temperature (OUT=0V)

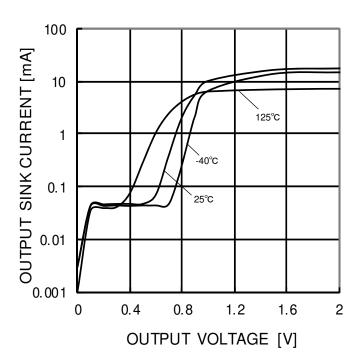


Figure 33.
Output Sink Current – Output Voltage (VCC=5V)

OBA2902Yxx-C

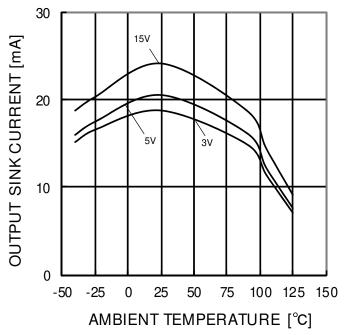


Figure 34.
Output Sink Current – Ambient Temperature
(OUT=VCC)

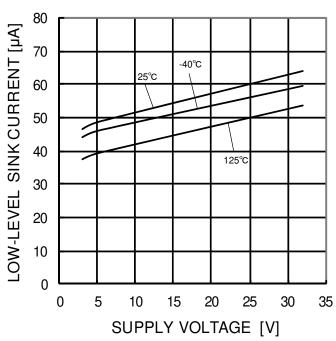


Figure 35.
Low Level Sink Current – Supply Voltage (OUT=0.2V)

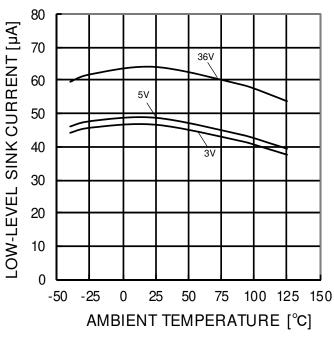


Figure 36.
Low Level Sink Current – Ambient Temperature (OUT=0.2V)

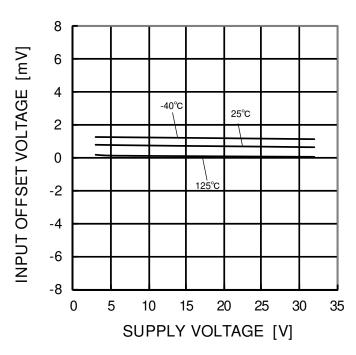
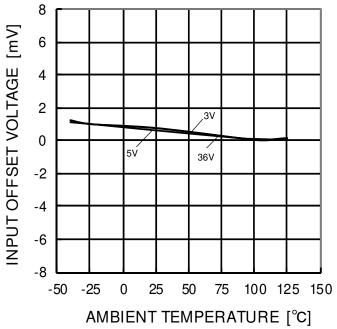


Figure 37.
Input Offset Voltage – Supply Voltage (Vicm=0V, OUT=1.4V)

OBA2902Yxx-C



50 INPUT BIAS CURRENT [nA] 40 30 25°C -40°C 20 10 125°C 0 5 0 10 15 20 25 30 35 SUPPLY VOLTAGE [V] Figure 39.

Input Bias Current - Supply Voltage

(Vicm=0V, OUT=1.4V)

Figure 38.
Input Offset Voltage – Ambient Temperature
(Vicm=0V, OUT=1.4V)

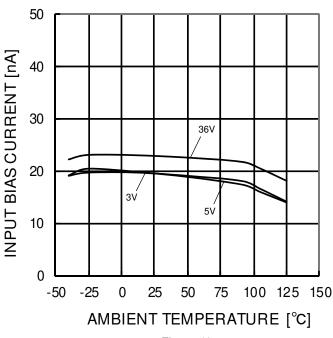


Figure 40.
Input Bias Current – Ambient Temperature (Vicm=0V, OUT=1.4V)

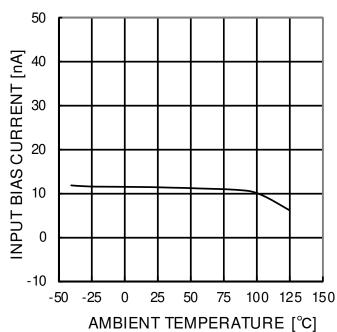


Figure 41.
Input Bias Current – Ambient Temperature (VCC=30V, Vicm=28V, OUT=1.4V)

OBA2902Yxx-C

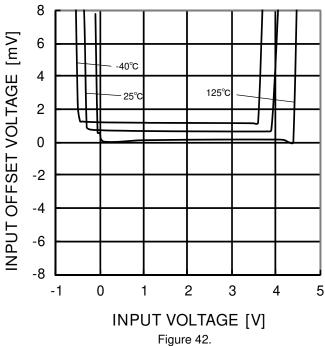


Figure 42.
Input Offset Voltage – Input Voltage (VCC=5V)

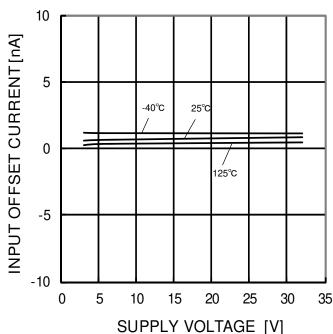


Figure 43.
Input Offset Current – Supply Voltage
(Vicm=0V, OUT=1.4V)

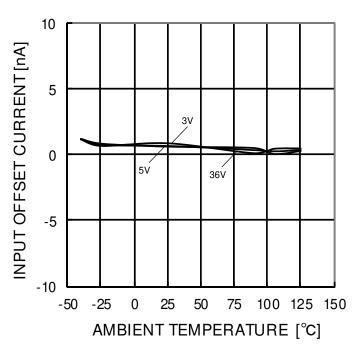


Figure 44.
Input Offset Current – Ambient Temperature
(Vicm=0V, OUT=1.4V)

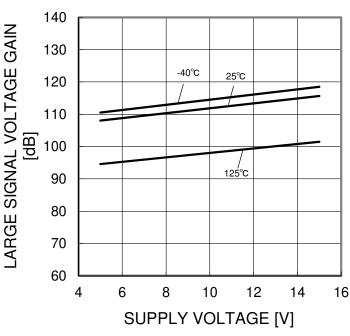


Figure 45.
Large Signal Voltage Gain – Supply Voltage  $(RL=2k\Omega)$ 

# ● Typical Performance Curves - Continued OBA2902Yxx-C

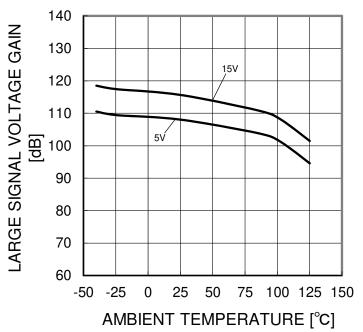


Figure 46.

Large Signal Voltage Gain – Ambient Temperature  $(RL=2k\Omega)$ 

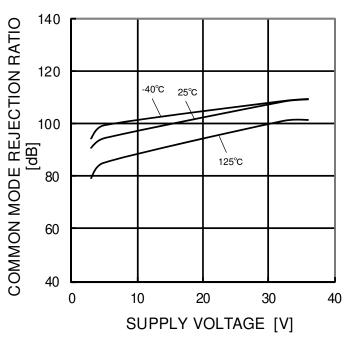


Figure 47.
Common Mode Rejection Ratio
– Supply Voltage

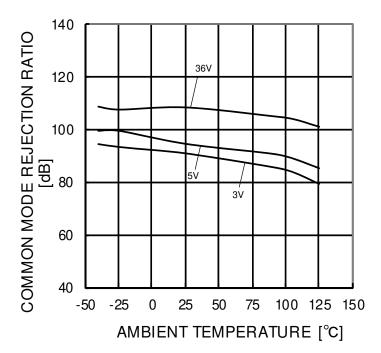


Figure 48.
Common Mode Rejection Ratio
– Ambient Temperature

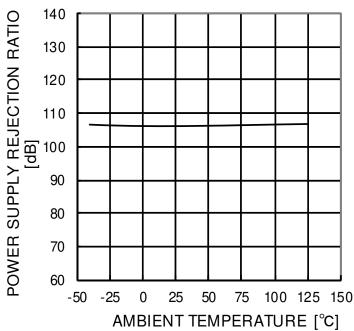


Figure 49.
Power Supply Rejection Ratio
– Ambient Temperature

## Power Dissipation

Power dissipation (total loss) indicates the power that the IC can consume at Ta=25°C (normal temperature). As the IC consumes power, it heats up, causing its temperature to be higher than the ambient temperature. The allowable temperature that the IC can accept is limited. This depends on the circuit configuration, manufacturing process, and consumable power.

Power dissipation is determined by the allowable temperature within the IC (maximum junction temperature) and the thermal resistance of the package used (heat dissipation capability). Maximum junction temperature is typically equal to the maximum storage temperature. The heat generated through the consumption of power by the IC radiates from the mold resin or lead frame of the package. Thermal resistance, represented by the symbol  $\theta$ ja°C/W, indicates this heat dissipation capability. Similarly, the temperature of an IC inside its package can be estimated by thermal resistance.

Figure 50. (a) shows the model of the thermal resistance of the package. The equation below shows how to compute for the Thermal resistance ( $\theta$ )a, given the ambient temperature (Ta), junction temperature (Tj), and power dissipation (Pd).

$$\theta$$
ja = (Tjmax - Ta) / Pd °C/W · · · · (I)

The Derating curve in Figure 50. (b) indicates the power that the IC can consume with reference to ambient temperature. Power consumption of the IC begins to attenuate at certain temperatures. This gradient is determined by Thermal resistance ( $\theta$ ja), which depends on the chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc. This may also vary even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Figure 51. (c),(d) shows an example of the derating curve for BA2904Yxxx-C, BA2902Yxx-C.

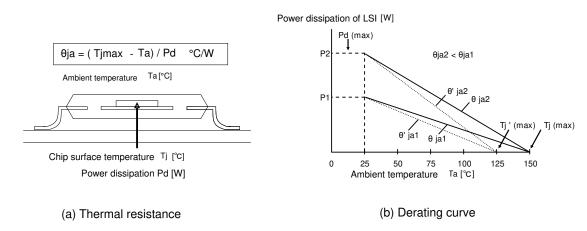
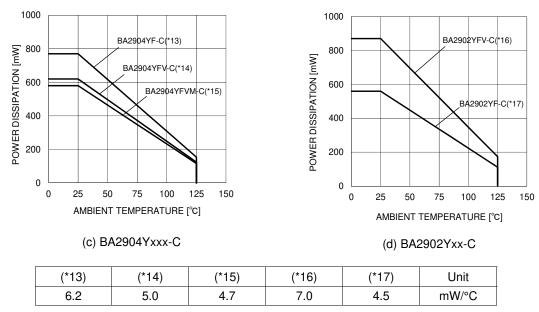


Figure 50. Thermal resistance and derating



When using the unit above Ta=25°C, subtract the value above per Celsius degree . Mounted on a FR4 glass epoxy board  $70 \, \text{mm} \times 70 \, \text{mm} \times 1.6 \, \text{mm}$  (cooper foil area below 3%)

Figure 51. Derating curve

# ● Application Information NULL method condition for Test circuit 1

LL method condition for Test Circuit 1 VCC. VEE. EK. Vicm Unit: V

							<b>v</b> 00,	,,	, VICITI OTIIL. V	
Parameter	VF	S1	S2	S3	VCC	VEE	EK	Vicm	calculation	
Input Offset Voltage	VF1	ON	ON	OFF	5 to 30	0	-1.4	0	1	
Input Offset Current	VF2	OFF	OFF	OFF	5	0	-1.4	0	2	
Input Bias Current	VF3	OFF	ON	OFF	5	0	-1.4	0	3	
mpat Blad Garront	VF4	ON	OFF	0		ŭ		Ŭ	Ü	
Large Signal Voltage Gain	VF5	ON	ON	N ON	15	0	-1.4	0	4	
Large digital voltage dalif	VF6	OIV	ON	ON	15	0	-11.4	0	<b>T</b>	
Common-mode Rejection Ratio	VF7	ON	ON	OFF	5	0	-1.4	0	5	
(Input common-mode Voltage Range)	VF8	CIN	CIN	011	5	0	-1.4	3.5		
Power Supply Rejection Ratio	VF9	ON	ON	OFF	5	0	-1.4	0	6	
1 ower Supply Hejection hatio	VF10	VF10 ON		5	30	0	-1.4	0	O	

- Calculation -
- 1. Input Offset Voltage (Vio)

$$Vio = \frac{|VF1|}{1 + RF/RS} [V]$$

2. Input Offset Current (lio)

$$lio = \frac{\left| VF2 - VF1 \right|}{Ri \times (1 + RF / RS)} \quad [A]$$

3. Input Bias Current (lb)

$$lb = \frac{|VF4-VF3|}{2 \times Ri \times (1+RF/RS)} [A]$$

4. Large Signal Voltage Gain (Av)

$$Av = 20 \times Log \frac{\Delta EK \times (1 + RF/RS)}{\mid VF5 - VF6 \mid} \quad [dB]$$

5. Common-mode Rejection Ration (CMRR)

$$CMRR = 20 \times Log \frac{\Delta Vicm \times (1 + RF/RS)}{|VF8 - VF7|} [dB]$$

6. Power supply rejection ratio (PSRR)

$$PSRR = 20 \times Log \frac{\Delta Vcc \times (1 + RF/RS)}{|VF10 - VF9|} \quad [dB]$$

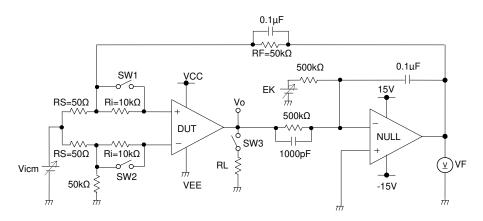


Figure . 52 Test circuit 1 (one channel only)

Toot	Circuit	9	Cwitch	Condition
iest	Carcuit	7	Switch	Condition

SW No.	SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7	SW 8	SW 9	SW 10	SW 11	SW 12	SW 13	SW 14
Supply Current	OFF	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Maximum Output Voltage (high)	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF
Maximum Output Voltage (Low)	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF
Output Source Current	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
Output Sink Current	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
Slew Rate	OFF	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	ON	ON	OFF	OFF	OFF
Gain Bandwidth Product	OFF	ON	OFF	OFF	ON	ON	OFF	OFF	ON	ON	ON	OFF	OFF	OFF
Equivalent Input Noise Voltage	ON	OFF	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF

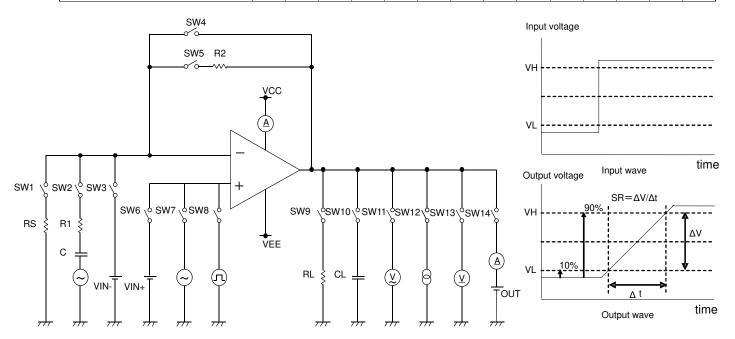


Figure . 53 Test Circuit 2 (each Op-Amp)

Figure . 54 Slew Rate Input Waveform

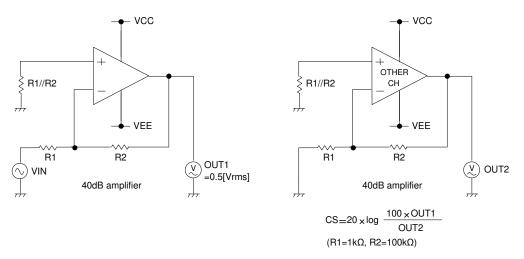


Figure . 55 Test Circuit 3(Channel Separation)

## Operational Notes

## 1) Unused circuits

When there are unused circuits, it is recommended that they are connected as in Figure .56, setting the non-inverting input terminal to a potential within the in-phase input voltage range (Vicm).

## 2) Input voltage

Applying VEE +36V to the input terminal is possible without causing deterioration of the electrical characteristics or destruction, regardless of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common mode input voltage range of the electric characteristics.

# Connect to Vicm VEE

Figure 56. Example of application circuit for unused op-amp

## 3) Power supply (single / dual)

The op-amp operates when the voltage supplied is between VCC and VEE. Therefore, the single supply op-amp can be used as dual supply op-amp as well.

## 4) Power Dissipation (Pd)

Using the unit in excess of the rated power dissipation may cause deterioration in electrical characteristics including reduced current capability due to the rise of chip temperature. Therefore, please take into consideration the power dissipation (Pd) under actual operating conditions and apply a sufficient margin in thermal design. Refer to the thermal derating curves for more information.

## 5) Short-circuit between pins and erroneous mounting

Be careful when mounting the IC on printed circuit boards. The IC may be damaged if it is mounted in a wrong orientation or if pins are shorted together. Short circuit may be caused by conductive particles caught between the pins.

## 6) Operation in a strong electromagnetic field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

#### Radioactive rays

This IC is not designed protection against radioactive rays.

## 8) IC handling

Applying mechanical stress to the IC by deflecting or bending the board may cause fluctuations of the electrical characteristics due to piezo resistance effects.

## 9) IC operation

The output stage of the IC is configured using Class C push-pull circuits. Therefore, when the load resistor is connected to the middle potential of VCC and VEE, crossover distortion occurs at the changeover between discharging and charging of the output current. Connecting a resistor between the output terminal and GND, and increasing the bias current for Class A operation will suppress crossover distortion.

## 10) Board inspection

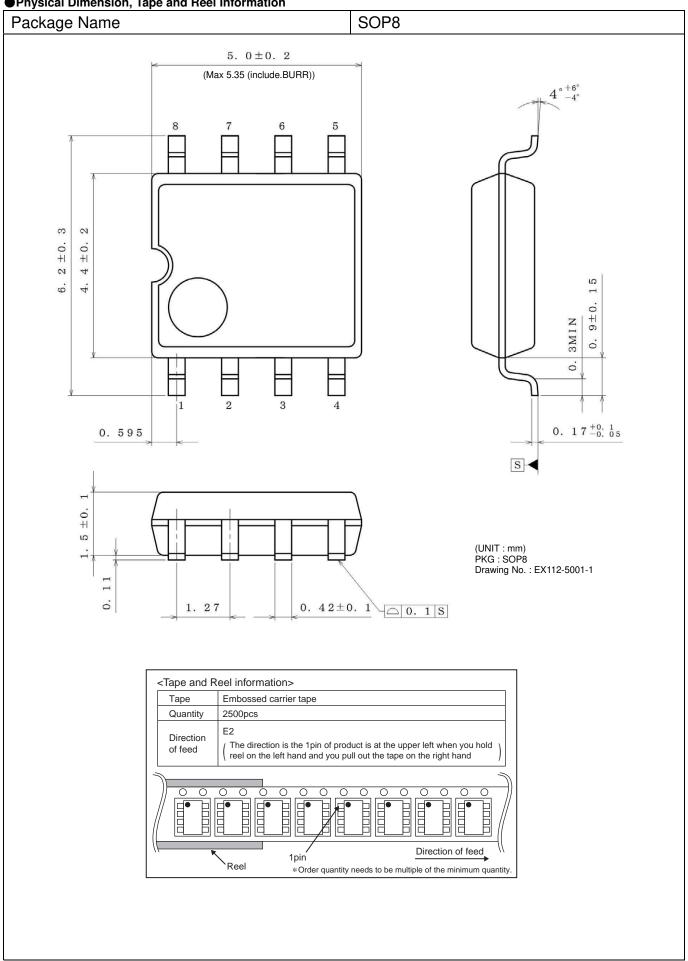
Connecting a capacitor to a pin with low impedance may stress the IC. Therefore, discharging the capacitor after every process is recommended. In addition, when attaching and detaching the jig during the inspection phase, make sure that the power is turned OFF before inspection and removal. Furthermore, please take measures against ESD in the assembly process as well as during transportation and storage.

## 11) Output capacitor

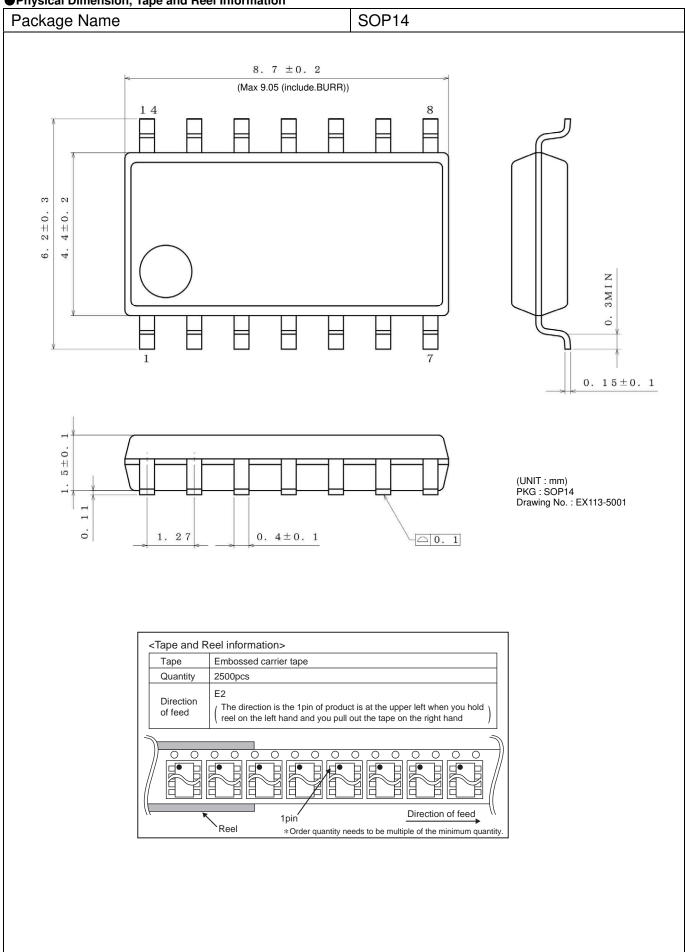
If a large capacitor is connected between the output pin and VEE pin, current from the charged capacitor will flow into the output pin and may destroy the IC when the VCC pin is shorted to ground or pulled down to 0V. Use a capacitor smaller than 0.1uF between output pin and VEE pin.

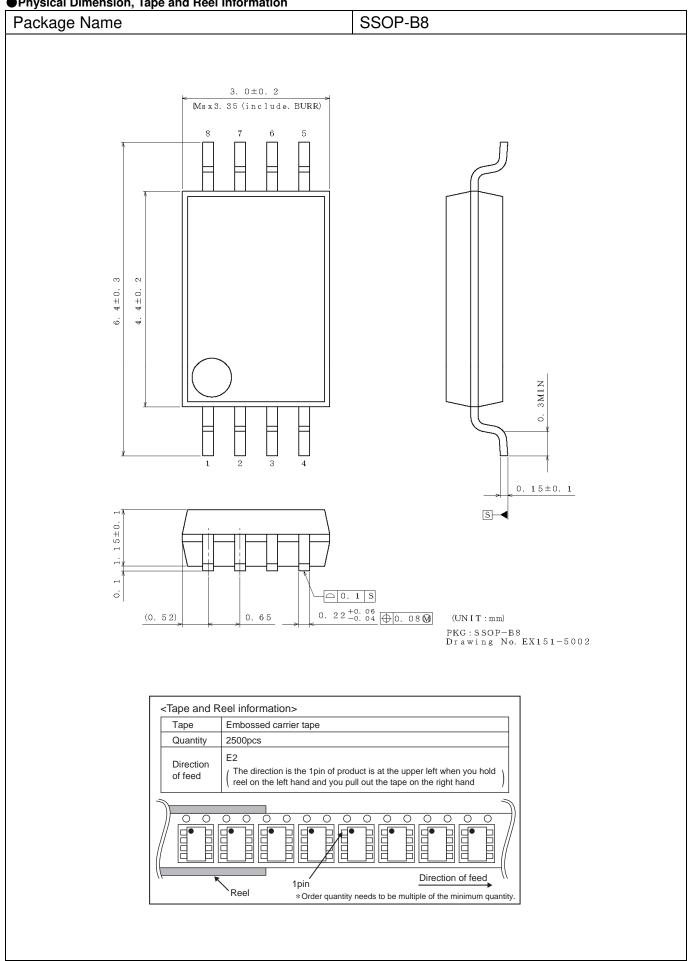
## 12) Oscillation by output capacitor

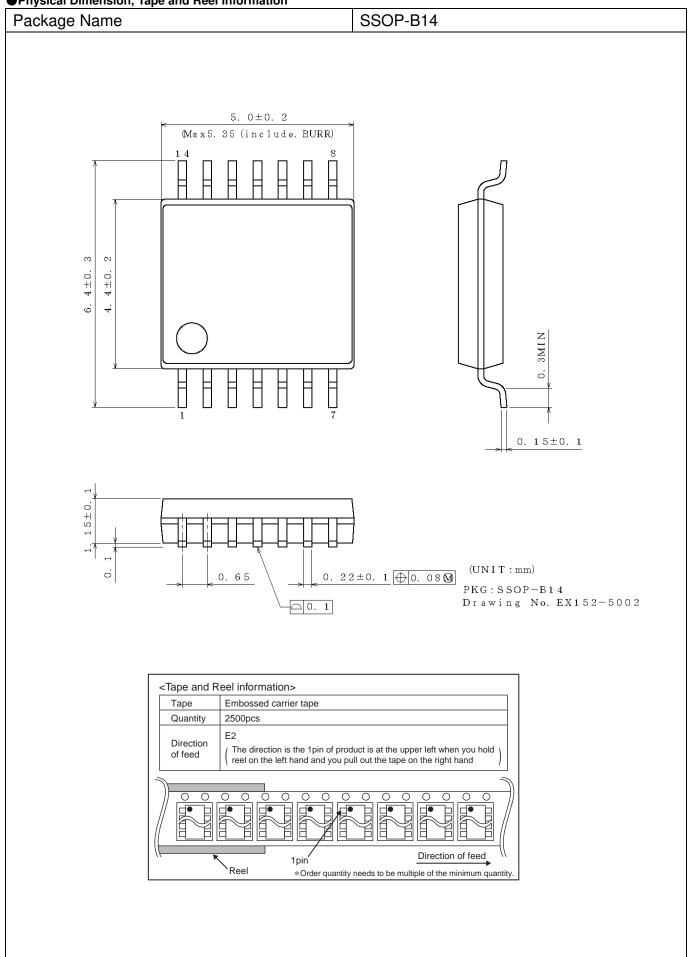
Please pay attention to the oscillation by output capacitor and in designing an application of negative feedback loop circuit with these ICs.

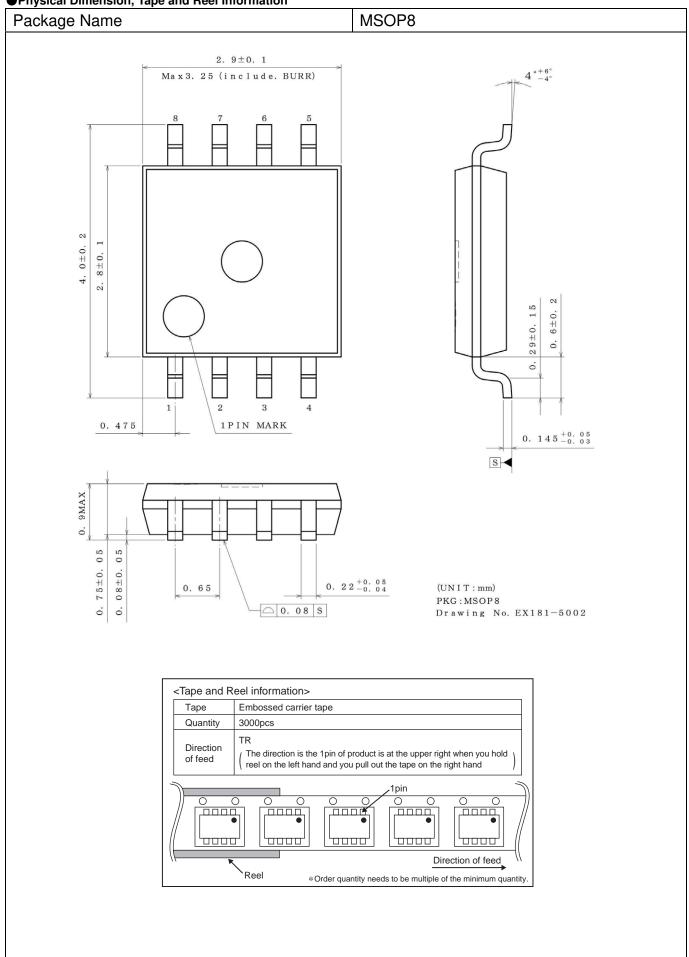




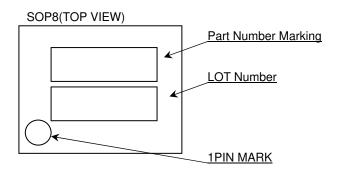


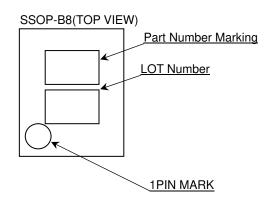


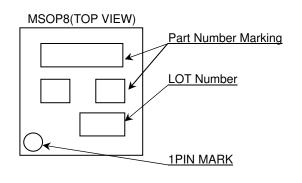


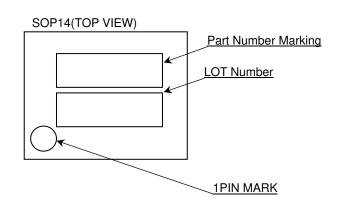


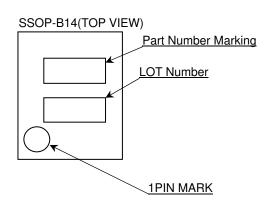
## Marking Diagrams





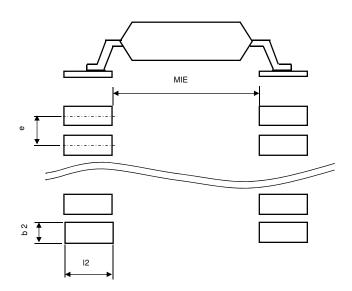






Product N	Name	Package Type	Marking
	F-C	SOP8	2904Y
BA2904Y	FV-C	SSOP-B8	04Y
	FVM-C	MSOP8	2904Y
BA2902Y	F-C	SOP14	BA2902YF
DAZJUZT	FV-C	SSOP-B14	2902Y

## ●Land pattern data



SOP8, SSOP-B8, MSOP8 SOP14, SSOP-B14

All dimensions in mm

Package	Land pitch e	Land space MIE	Land length ≧ℓ 2	Land width b2
SOP8 SOP14	1.27	4.60	1.10	0.76
SSOP-B8 SSOP-B14	0.65	4.60	1.20	0.35
MSOP8	0.65	2.62	0.99	0.35

Revision History

10 1101011 1110101 y			
Date	Revision	Changes	
5.MAR.2012	001	New Release	
21.JAN.2013	002	Land pattern data inserted.	
11.MAR.2013	003	Input offset voltage, Input offset current limit (Temp=25°C) changed.  Description of Physical Dimension, Tape and Reel Information changed.	
8.MAY.2013	004	SOP8, SSOP-B8, MSOP8 Power dissipation corrected. SSOP-B8 Description of Physical Dimension corrected.	

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(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSII	CLASS II b	CLASSII
CLASSIV		CLASSⅢ	

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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